CHIPQUIK® REM16-ULTRA-NL

Datasheet revision 1.0

www.chipquik.com

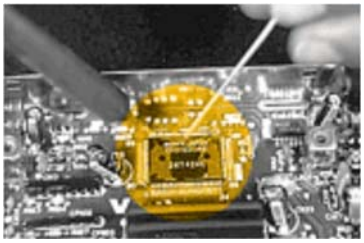
Ultra-Low Temp Flux-Cored Chip Removal Alloy Lead-Free 16 FT

Product Highlights

Easily remove SMD parts with **Chip Quik® ULTRA** removal alloy
Reduce heat and reduce damage to circuit boards and SMD parts during removal
Revolutionary 3% Flux-Cored Removal Alloy!
Melts at only 62 Celsius (144 Fahrenheit)!
Lead-Free!
RoHS 3 and REACH compliant
Easy clean-up of left-over flux residue using hot water (60°C+)

Specifications

Alloy:	**Chip Quik**® ULTRA™ Alloy Lead-Free 30-6.5in. Sticks
Alloy Melting Point:	62°C (144°F)
Flux Core:	3% No-Clean Water-Washable Synthetic
Flux Classification:	REL0
Flux Activation Temperature:	140°C (284°F)

Chip Quik® ULTRA Instructions		
	1	Melt Chip Quik low temperature ULTRA alloy uniformly on all pins of SMD. Maintain alloy in molten state long enough for complete reflow.
	2	Lift chip from board with dental pick or vacuum pen.
	3	Thoroughly clean site with hot water (60°C+).

SMD Removal

(With solder iron or warm air bath)

- Apply flux to all leads.
- Melt CHIP QUIK® uniformly on all pins.
- Maintain alloy in molten state long enough to release chip.
- Lift chip from board with dental pick or vacuum pen.

CLEAN UP

- While molten, use cotton swab and flux to move excess to an unused section of board.
- While applying heat, polish each pad with a swab and flux until thoroughly clean.
- At room temperature, clean residue with alcohol pad.
- You are now ready to install the new chip.

30-6.5” Sticks of Chip Quik® material, removes 7,500 to 9,000 SMD pins.

Conforms to the following Industry Standards:

J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	Yes
RoHS 3 Directive (EU) 2015/863:	Yes